									ONS										
LTR	DESCRIPTION							DATE (YR-MO-DA)			APPROVED								
А		hange to 355 ro	TCV <sub>O</sub> te	est as s	pecified	under	table I.	Repla	ace CA	GE 066	65	00-01-11			R. M	NIN			
В	Replace	e referen	ce to MIL	-STD-9	973 with	refere	nce to	MIL-PF	RF-3853	35 ro	0		07-0	)2-21			J. ROD	ENBEC	K
С	Add dev and Tab	vice type ble IIB. A	s 02, 03, dd footn	04, cas ote unc	se outlir ler Tabl	ne H, ra le I ro	diation	harder	ned req	uireme	ents,		17-0	)1-19			C. SA	AFFLE	
D	Make correction to Output voltage (VO) units column from "mV" to "V" as specified under Table IIB ro						17-0	)3-15			C. SA	AFFLE							
THE ORIGINA REV SHEET REV SHEET	L FIRST SI	HEET O	THIS D	RAWIN	NG HAS	BEEN	REPL	ACED.											
REV SHEET REV		HEET O	THIS D			BEEN	REPL	ACED.	D		D	D	D	D	D				
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REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A		) ) ) ) ) )	REV SHE PRE RIC CHE	V EET EPAREI CK C. C	D BY	D 1	D	D	D		6 CC	7 DLA I DLUM	8 LAND IBUS,	9 AND , OHIO	10 MAF D 432	11 RITIM 218-3	12 E		
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DRA THIS DRAWII FOR U	NDARD OCIRCU AWING NG IS AVA JSE BY ALL ARTMENTS NCIES OF	) JIT NILABLE L S THE	REV SHE PRE RIC CHE CH APP MIC	V EET EPAREI CK C. C ECKED IARLES PROVEI CHAEL	D BY DFFICEI BY S E. BES D BY A. FRY	D 1 R SORE	D 2	D	D 4 MIC PRE	5 ROC ECISI	6 CC <u>http:</u>	7 DLA I DLUM //www	8 BUS, w.land	9 AND OHIC dandi	10 0 MAF 0 432 mariti	11 218-39 ime.d	12 E 990 Ia.mil	WER	
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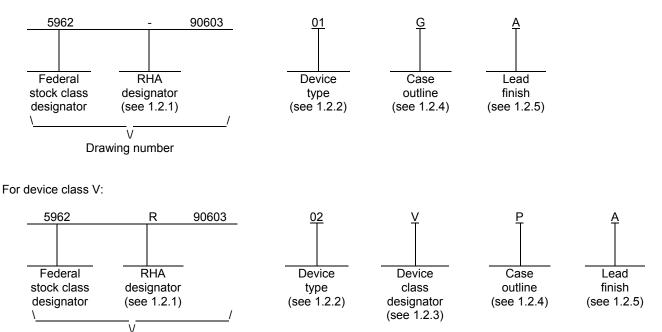
DISTRIBUTION STATEMENT A. Approved for public release. Distribution is unlimited.

## 1. SCOPE

1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device class Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 <u>PIN</u>. The PIN is as shown in the following examples.

For device class M and Q:



Drawing number

1.2.1 <u>RHA designator</u>. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	REF43	+2.5 V low power precision voltage reference
02	REF43	+2.5 V low power precision voltage reference
03	REF43	+2.5 V low power precision voltage reference
04	REF43	+2.5 V low power precision voltage reference

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as listed below. Since the device class designator has been added after the original issuance of this drawing, device classes M and Q designators will not be included in the PIN and will not be marked on the device.

Device class Device requirements documentation						
М		Vendor self-certification to the requirements for MIL-STD-883 compliant, non- JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A				
Q or V	Certification and	qualification to M	IL-PRF-38535			
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DLA LAND AND MA COLUMBUS, OHIO 43	· · · · · · · · · · · · · · · · · · ·		REVISION LEVEL	SHEET 2		

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows: **Outline letter** Descriptive designator Terminals Package style G MACY1-X8 8 Can GDFP1-F10 Н 10 Flat pack GDIP1-T8 or CDIP2-T8 Р 8 Dual-in-line 2 CQCC1-N20 20 Square leadless chip carrier 1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535. appendix A for device class M. 1.3 Absolute maximum ratings. 1/ Input voltage (VIN) ...... 40 V dc Output short circuit duration ...... Indefinite -65°C to +150°C Lead temperature (soldering, 60 seconds) ..... +300°C DICE junction temperature range (TJ) : Cases G, P, and 2 ...... -65°C to +150°C Case H ..... +175°C Thermal resistance, junction-to-case ( $\theta$ JC) Cases G, P, and 2 ..... See MIL-STD-1835 Case H ..... 22°C/W maximum Thermal resistance, iunction-to-ambient ( $\theta$ JA): Case G ..... 150°C/W maximum Case H ..... 141°C/W maximum Case 2 ..... 110°C/W maximum 1.4 Recommended operating conditions. Load current (IL) ...... 0 mA 1.5 Radiation features. Maximum total dose available (dose rate = 50 - 300 rad(Si)/s) : Maximum total dose available (dose rate  $\leq$  10 mrad(Si)/s) : Device type 04 ...... 50 krad(Si) 3/ 1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability. 2/ Device types 02 and 03 may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions as specified in MIL-STD-883, method 1019, condition A for device types 02 and 03. For device type 04 radiation end point limits for the noted parameters are guaranteed for the conditions specified in 3/ MIL-STD-883, method 1019, condition D. SIZE STANDARD 5962-90603 Α **MICROCIRCUIT DRAWING** DLA LAND AND MARITIME **REVISION LEVEL** SHEET COLUMBUS, OHIO 43218-3990 3 D

## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

#### DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 -	Test Method Standard Microcircuits.	
MUL OTD 4005	Interface Oten dead Electronic Ocean en est Ocean	

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <u>http://quicksearch.dla.mil</u> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 <u>Case outlines</u>. The case outlines shall be in accordance with 1.2.2 herein.

3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.

3.2.3 <u>Radiation exposure circuit</u>. The radiation exposure circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing and acquiring activity upon request.

3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

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3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 <u>Notification of change for device class M</u>. For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 <u>Verification and review for device class M</u>. For device class M, DLA Land and Maritime, DLA Land and Maritime 's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 <u>Microcircuit group assignment for device class M</u>. Device class M devices covered by this drawing shall be in microcircuit group number 59 (see MIL-PRF-38535, appendix A).

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Test	Symbol	-55°C ≤ T Vin :	ons <u>1/ 2</u> / A ≤ +125°C = +5 V	Group A subgroups	Device type	Lim	nits	Unit
		unless other	wise specified			Min	Max	
Output adjustment <u>3</u> / range				1	01, 02, 03, 04	±3		%
Load current <u>4</u> /	۱L			1	01, 02, 03, 04	10		mA
Quiescent supply current	ISY			1	01, 02,		450	μA
(no load)				2,3	03, 04		600	
			M,D,L,R	1	02, 03		450	
			M,D,L	1	04		450	
Output voltage	Vo			1	01, 02,	2.4975	2.5025	V
(no load)				2,3	03, 04	2.495	2.505	
			M,D,L,R	1	02, 03	2.49	2.5025	
			M,D,L	1	04	2.49	2.5025	
Short circuit current 3/	ISC	V0 = 0 V		1	01, 02,		100	mA
				2,3	03, 04		120	
Load regulation	LDreg	IL = 0 mA to	10 mA	1	01, 02,		20	ppm /
	0				03, 04		28	mA
				2,3	01, 02,		40	
					03, 04		50	
			M,D,L,R	1	02		60	
					03		70	
			M,D,L	1	04		70	
Line regulation	LNreg	VIN = 4.5 V to	o 40 V	1	01, 02,		2	ppm/V
				2,3	03, 04		3	
			M,D,L,R	1	02, 03		100	
			M,D,L	1	04		100	
Temperature voltage <u>3</u> /	VT			1	01, 02,	0.54	0.58	V
output				2	03, 04	0.72	0.78	
				3		0.38	0.43	
See footnotes at end of table	 e.			3		0.38	0.43	<u> </u>

SIZE

# TABLE I. <u>Electrical performance characteristics</u> - continued.

Test	Symbol	Conditions <u>1/ 2/</u> -55°C ≤ TA ≤ +125°C VIN = +5 V	Group A subgroups	Device type	Limits		Unit		
		unless otherwise specified			Min	Max			
Output voltage <u>5</u> /	TCVO		8	01		16	ppm /		
temperature coefficient				02, 03, 04		15	°C		
Wideband output voltage noise	enRMS		7	01, 02, 03, 04		10	μVRMS		

- 1/ Device types 02 and 03 are supplied to this drawing has been characterized through all levels M, D, L, R of irradiation and tested at the "L and R" levels. Device type 04 has been characterized through levels M, D, and L and is tested at the "L" level. Pre and Post irradiation values are identical unless otherwise specified in Table I. When performing post Irradiation electrical measurements for any RHA level, TA = +25°C.
- 2/ Device types 02 and 03 may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, method 1019, condition A for device types 02, 03 and condition D for device type 04. Device type 04 has been tested at low dose rate condition D of MIL-STD-883, method 1019.
- 3/ Not tested post irradiation.
- 4/ Guaranteed by load regulation ( LDreg ) test.
- <u>5</u>/ Output voltage temperature coefficient is measured by the box method. The tempco is defined as the slope of the diagonal of a box drawn around the output voltage plotted against temperature. VOUT is measured at TMIN, 25°C, and TMAX for the applicable temperature range. The lowest of these three readings is subtracted from the highest reading and the resulting difference is divided by (TMAX TMIN).

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Device type	01, 02	03, 04	01
Case outlines Terminal	G and P	Н	2
number		Terminal symbol	
1	TEST (see note)	TEST	NC
2	Vin	VIN	TEST (see note)
3	TEMP	TEMP	NC
4	GND	NC	NC
5	TRIM	GROUND	VIN
6	Vout	TRIM	NC
7	NC	NC	TEMP
8	TEST (see note)	Vout	NC
9		NC	NC
10		TEST	GND
11			NC
12			TRIM
13			NC
14			NC
15			Vout
16			NC
17			NC
18			NC
19			NC
20			TEST (see note)

NC = No connection Note: Make no electrical connection to these pins because they are reserved for factory testing.

FIGURE 1. Terminal connections.

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#### 4. VERIFICATION

4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

#### 4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015.
  - (2) T<sub>A</sub> = +125°C, minimum.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.

## 4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

## 4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 4, 5, 6, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

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Test requirements	Subgroups (in accordance with MIL-STD-883,	Subgroups (in accordance with MIL-PRF-38535, table III)	
	method 5005, table I) Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1		1
Final electrical parameters (see 4.2)	1, 2, 3, 8 <u>1</u> /	1, 2, 3 <u>1</u> /	1, 2, 3 <u>1</u> / <u>2</u> /
Group A test requirements (see 4.4)	1, 2, 3, 7, 8	1, 2, 3, 7, 8	1, 2, 3, 7, 8
Group C end-point electrical parameters (see 4.4)	1	1, 2, 3	1, 2, 3 <u>2</u> /
Group D end-point electrical parameters (see 4.4)	1	1, 2, 3	1, 2, 3
Group E end-point electrical parameters (see 4.4)			1

TABLE IIA. Electrical test requirements.

1/ PDA applies to subgroup 1.

2/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be computed with reference to the previous interim electrical parameters.

TABLE IIB.	Burn-in and	operating I	ife test delta	parameters.	TA = +25°C.
------------	-------------	-------------	----------------	-------------	-------------

Test	Symbol	Burn in end points		Life test end points		Delta	Units
	-,	Min	Max	Min	Max		
Output voltage	Vo	2.4975	2.5025	2.495	2.505	±0.0025	V
Supply current	ISY		450		495	±45	μA

4.4.2 <u>Group C inspection</u>. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b.  $TA = +125^{\circ}C$ , minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 <u>Additional criteria for device classes Q and V</u>. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

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4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at TA = +25°C ±5°C, after exposure, to the subgroups specified in table IIA herein.

4.4.4.1 <u>Total dose irradiation testing</u>. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019, condition A for device types 02 and 03, condition D for device type 04, and as specified herein.

## 5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

## 6. NOTES

6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractorprepared specification or drawing.

6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 <u>Record of users</u>. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 <u>Comments</u>. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

#### 6.6 Sources of supply.

6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

6.6.2 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

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## 6.7 Application notes.

6.7.1 <u>Output decoupling</u>. For device types 02, 03 and 04, output decoupling is not generally required or recommended on the device. In applications that require output decoupling, care will need to be taken when choosing the capacitor due to the equivalent series resistance (ESR) of the capacitor. If capacitors with very low ESR are chosen it may be necessary to add some additional resistance in series with the capacitor to limit the initial charge current when power is applied to the device. Adding series resistance when low ESR capacitors are used will help with the stability of the device when power is applied over the entire temperature range.

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## STANDARD MICROCIRCUIT DRAWING BULLETIN

## DATE: 17-03-15

Approved sources of supply for SMD 5962-90603 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <a href="https://landandmaritimeapps.dla.mil/Programs/Smcr/">https://landandmaritimeapps.dla.mil/Programs/Smcr/</a>.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-9060301GA	<u>3</u> /	REF43BJ/883
5962-9060301PA	<u>3</u> /	REF43BZ/883
5962-90603012A	<u>3</u> /	REF43BRC/883
5962R9060302VPA	24355	REF43AZ/QMLR
5962R9060303VHA	24355	REF43AL/QMLR
5962L9060304VHA	24355	REF43AL/QMLL

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE <u>number</u>

24355

Vendor name and address

Analog Devices Route 1 Industrial Park P.O. Box 9106 Norwood, MA 02062 Point of contact: 7910 Triad Center Drive Greensboro, NC 27409-9605

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.